



Material Content Data Sheet



Sales Product Name	TLE4263-2ES			Issued	25. January 2018			
MA#	MA001674310							
Package	PG-DSO-8-27			Weight*	84.55 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.136	3.71	3.71	37091	37091
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.728	0.86		8607	
wire	non noble metal	copper	7440-50-8	29.548	34.95	35.86	349465	358610
	noble metal	gold	7440-57-5	0.147	0.17	0.17	1735	1735
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.11		1135
encapsulation	plastics	epoxy resin	-	4.413	5.22		52188	
	inorganic material	silicondioxide	60676-86-0	43.454	51.40	56.73	513935	567258
leadfinish	non noble metal	tin	7440-31-5	0.695	0.82	0.82	8221	8221
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8569	8569
glue	plastics	epoxy resin	-	0.391	0.46		4629	
	noble metal	silver	7440-22-4	1.174	1.39	1.85	13887	18516
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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